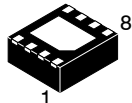


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®



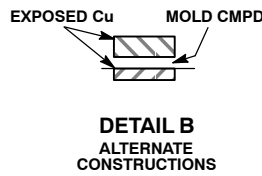
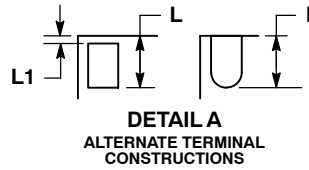
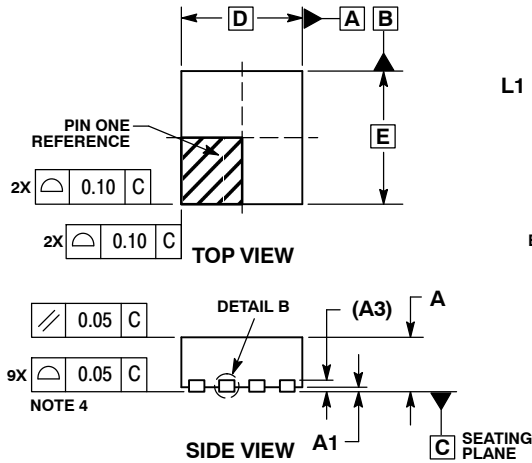
SCALE 4:1

DFN8, 2.0x2.2, 0.5P

CASE 506BP-01

ISSUE A

DATE 13 JAN 2010

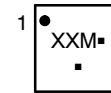


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

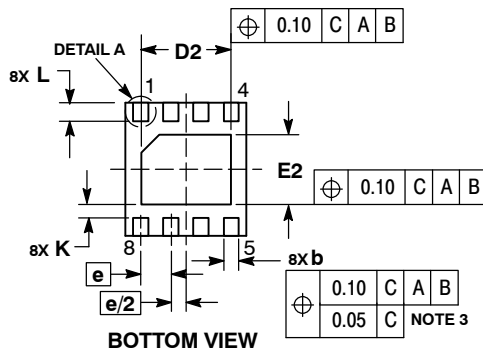
DIM	MILLIMETERS		
	MIN	TYP	MAX
A	0.80	---	1.00
A1	0.00	---	0.05
A3	0.20 REF		
b	0.20	---	0.30
D	2.00 BSC		
D2	1.43	---	1.53
E	2.20 BSC		
E2	1.05	---	1.25
e	0.50 BSC		
K	0.20	0.22	0.30
L	0.25	---	0.35
L1	---	---	0.15

GENERIC MARKING DIAGRAM*

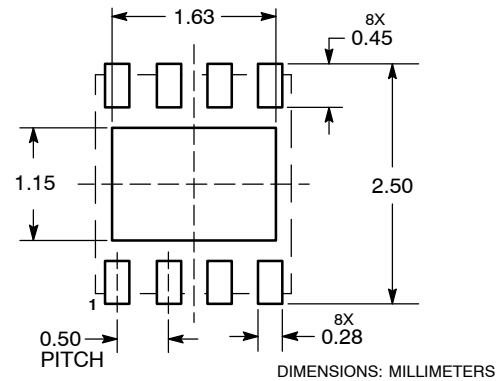


- XX = Specific Device Code
- M = Date Code
- = Pb-Free Device

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present.



SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	DFN8, 2.0X2.2, 0.5P	PAGE 1 OF 2

